

DATASHEET

Technical Data Sheet SMD B IRR15-22C/L491/TR8

Features

- Low forward voltage
- Good spectral matching to Si photodetector
- Pb free
- The product itself will remain within RoHS compliant version.
- Compliance with EU REACH.
- Compliance Halogen Free .(Br <900 ppm ,Cl <900 ppm , Br+Cl < 1500 ppm)

Description

• IRR15-22C/L491/TR8 is an infrared emitting diode and red emitting diode in miniature top view flat SMD package and it is molded in a water clear plastic. The device is spectrally matched with silicon photodiode and phototransistor.

Applications

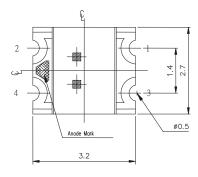
• Infrared applied system

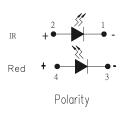
Device Selection Guide

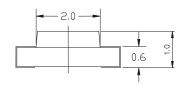
| Device No. | Chip Material | Lens Color |
|------------|---------------|-------------|
| IR | GaAlAs | Water clear |
| Red | AlGaInP | Water clear |



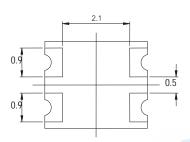
Package Dimensions

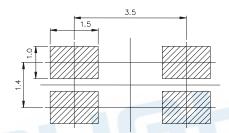






For Reflow Sodering





Notes: 1.All dimensions are in millimeters 2.Tolerances unless dimensions ±0.1mm

Absolute Maximum Ratings (Ta=25°C)

Notes: *1:Soldering time ≤ 5 seconds.

| Parameter | Symbol | Rating | Unit |
|--|------------------|------------|------|
| Continuous Forward Current (IR) | I _F | 50 | mA |
| Continuous Forward Current (Red) | I _F | 50 | mA |
| Reverse Voltage | V_{R} | 5 | V |
| Operating Temperature | T _{opr} | -25 ~ +85 | °C |
| Storage Temperature | T _{stg} | -40 ~ +100 | °C |
| Soldering Temperature *1 | T _{sol} | 260 | °C |
| Power Dissipation at(or below) 25°C Free Air Temperature for IR | P _c | 100 | mW |
| Power Dissipation at(or below) 25°C Free Air Temperature for Red | P _c | 130 | mW |

Notes: *1: Soldering time ≤ 5 seconds.



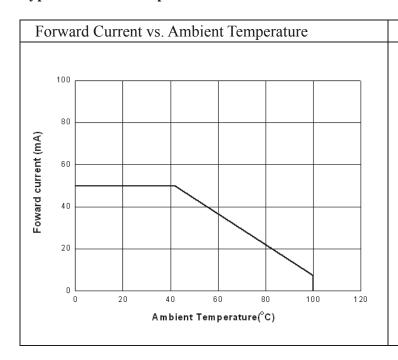
Electro-Optical Characteristics (Ta=25°C unless specified otherwise)

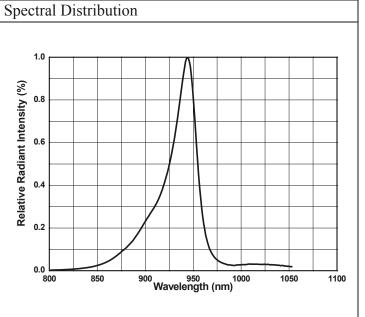
| Parameter | Symbol | Min. | Тур.* | Max. | Unit | Condition |
|-------------------------|-------------------|------|-------|------|-------|----------------------|
| Radiant Intensity (IR) | I _E | 1.0 | 2.1 | | mW/sr | I _F =20mA |
| Radiant Intensity (Red) | Ι _Ε | 1.0 | 2.3 | | mW/sr | I _F =20mA |
| Peak Wavelength (IR) | λp | | 940 | | nm | I _F =20mA |
| Peak Wavelength (Red) | λp | 657 | 660 | 663 | nm | I _F =20mA |
| Spectral Bandwidth (IR) | Δλ | | 30 | | nm | I _F =20mA |
| Spectral Bandwidth (IR) | Δλ | | 20 | | nm | I _F =20mA |
| Forward Voltage (IR) | V_{F} | | 1.30 | 1.70 | V | I _F =20mA |
| Forward Voltage (Red) | V_{F} | | 1.90 | 2.50 | V | I _F =20mA |
| Reverse Current | I _R | | | 10 | μΑ | V _R =5V |
| View Angle | 2θ _{1/2} | | 120 | | Deg. | I _F =20mA |

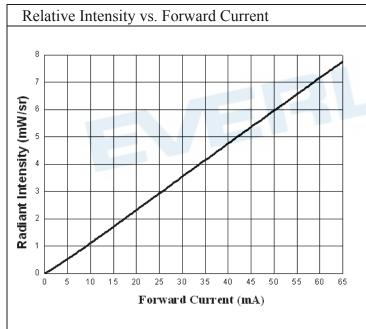


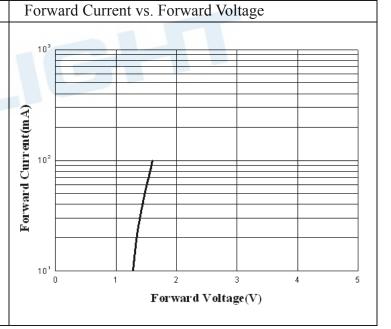


Typical Electrical/Optical/Characteristics Curves for IR



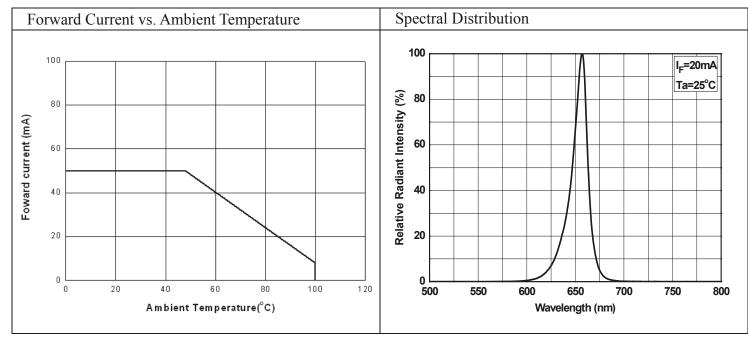


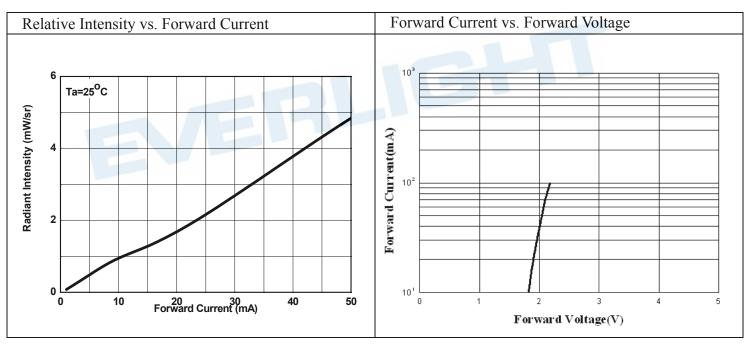


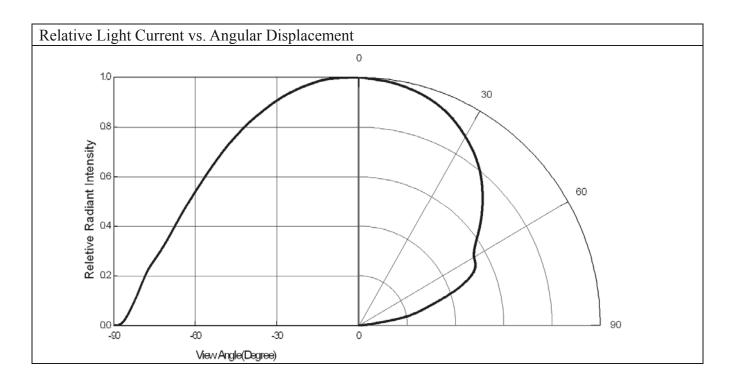




Typical Electrical/Optical/Characteristics Curves for Red











Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

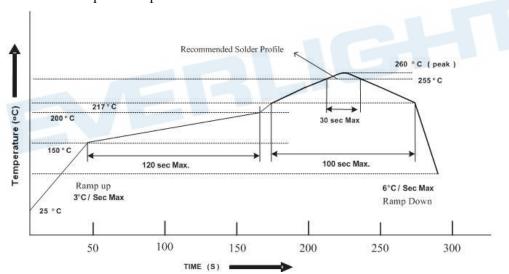
2. Storage

- 2.1 Do not open moisture proof bag before the products are ready to use.
- 2.2 Before opening the package, the LEDs should be kept at 30°C or less and 90%RH or less.
- 2.3 The LEDs should be used within a year.
- 2.4 After opening the package, the LEDs should be kept at 30°C or less and 60%RH or less.
- 2.5 The LEDs should be used within 168 hours (7 days) after opening the package
- 2.6 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for Min. 24 hours.

3. Soldering Condition

3.1 Pb-free solder temperature profile



- 3.2 Reflow soldering should not be done more than two times.
- 3.3 When soldering, do not put stress on the LEDs during heating.
- 3.4 After soldering, do not warp the circuit board.

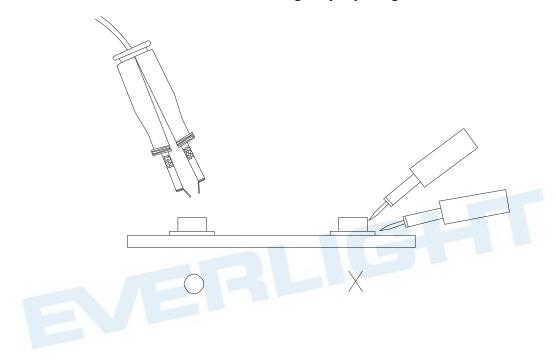


4. Soldering Iron

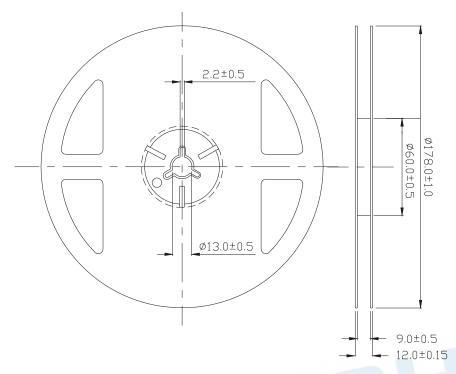
Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.

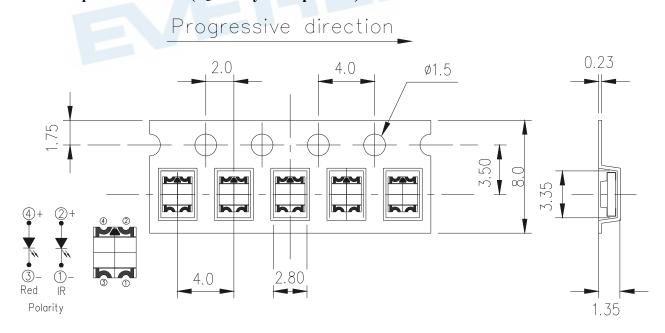


Package Dimensions



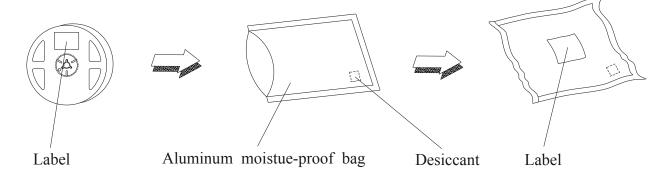
Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm

Carrier Tape Dimensions: (Quantity: 2000pcs/reel)

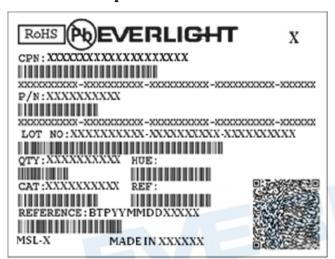


Note: The tolerances unless mentioned is ± 0.1 mm, Unit = mm

Packing Procedure



Label Form Specification



CPN: Customer's Production Number

P/N : Production Number QTY: Packing Quantity

CAT: Ranks

HUE: Peak Wavelength

REF: Reference

LOT No: Lot Number

MADE IN TAIWAN: Production Place

DISCLAIMER

- 1. EVERLIGHT reserves the right(s) on the adjustment of product material mix for the specification.
- 2. The product meets EVERLIGHT published specification for a period of twelve (12) months from date of shipment.
- 3. The graphs shown in this datasheet are representing typical data only and do not show guaranteed values.
- 4. When using this product, please observe the absolute maximum ratings and the instructions for using outlined in these specification sheets. EVERLIGHT assumes no responsibility for any damage resulting from the use of the product which does not comply with the absolute maximum ratings and the instructions included in these specification sheets.
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